

DFL7362

Fully Automatic Laser Saw

Laser saw compatible with various processes which achieves high-speed, high-quality processing of ultra-thin Si

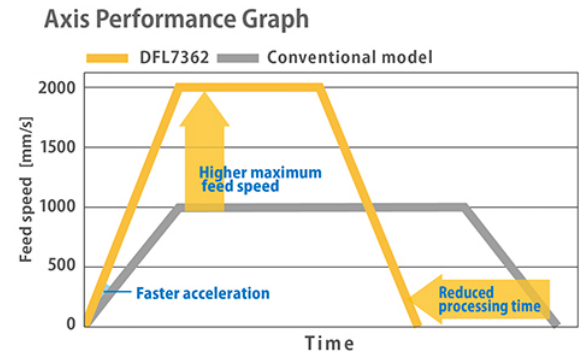
Φ300 mm Stealth Dicing™ SDBG SDTT

- DFL7362 is a fully-automatic laser saw for Φ300 mm wafers used mainly to singulate ultra-thin Si wafers.
- Si with a thickness of 50 μm or less can be singulated at high speed while maintaining high die strength.
- The equipment offers both wafer and frame transferring, making it possible to support a wide range of applications.



High throughput

UPH is improved by approx. 30% through increased maximum X-axis speed and acceleration in addition to reduced wafer transfer and alignment times.



Wide range of options

DFL7362 is compatible with a wide range of options related to quality and productivity, such as wafer thickness measurement and non-stop kerf check.

Specifications

Specification		Unit	
Processing method		-	Stealth Dicing™
Max. workpiece size		mm	Φ300
X-axis (Chuck table)	Processing range	mm	310
	Moving speed	mm/s	0.1 ~ 2,000
Y-axis (Chuck table)	Processing range	mm	310
	Index step	mm	0.0001
	Positioning accuracy	mm	0.003/310 (Single error)0.002/5
Z-axis	Moving resolution	mm	0.000005
	Repeatability accuracy	mm	0.001
θ-axis (Chuck table)	Max. rotating angle	deg	380
Machine dimensions (W×D×H)		mm	1,600 × 2,755 × 1,800
Machine weight		kg	Approx. 2,850

*Product appearance, features, specifications, and other details may change due to technical modifications.
*Please read the standard specification sheet thoroughly before use.

Product Lineup



DFL7341

Machine type	Fully Automatic
Method	Stealth Dicing™
Machine dimentions (W × D × H)	950 × 1,732 × 1,800
Machine weight (kg)	1,800

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